ナノ粒子
Nano Particle

銅ナノ粒子 SFCP series
Cu nano particle SFCP series

特長 *Advantages*

SFCP-10A/10AX は、 メタノールに湿潤・分散させた一次粒子径約 50 nm の銅ナノ粒子です※
SFCP series are wetted and dispersed in methanol. The particle size is about 50 nm.
※導電性銅ナノインクではありません。 お客様で導電性インク等にして頂く必要があります。
This product is not a conductive copper nano ink, so the customer needs to make it a conductive ink.

SFCP-10A

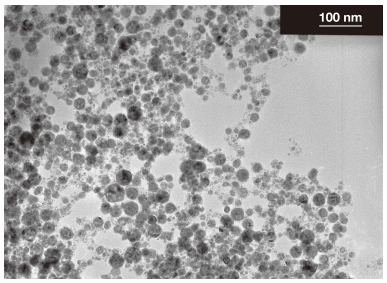
■**粒子径約 *50 nm* の一次粒子を約 *10 ～ 20 μm* の顆粒状に凝集**
Aggregates into granules (average particle size 10-20 μm).

■**導電材料の他、 放熱・抗菌・触媒開発用途へ**
Suitable for electrical conductive, thermal conductive and antibacterial applications and catalysts.

SFCP-10AX

■**メタノール中に均一分散し、 配線用銅ナノインク開発に最適**
Uniformly dispersed in methanol, making it ideal for developing copper.

■**低温・短時間還元雰囲気で低抵抗銅導体膜化が可能**
Copper conductive film with low resisting can be formed in reducing atmosphere at low temperature and for short time.



***SFCP-10AX TEM* 像**
TEM image of SFCP-10AX

Cu_2O ナノ粒子インク DC series
Cu_2O nano particle ink DC series

特長 *Advantages*

粒子径 50 ～ 100 nm 程度で不規則形状の Cu_2O ナノ粒子をケトン系溶媒中に分散した高濃度インク
Highly concentrated ink with irregularly shaped Cu_2O nanoparticles size of 50 to 100 nm particle size dispersed in a ketone-based solvent.

低温度の導体化処理で、 低抵抗の銅導体膜化が可能
Achieving a low-resistance conductive film even through low-temperature conductive processing.

長期間、 安定な分散状態を維持
Maintaining a stable dispersion state for a long period of time.

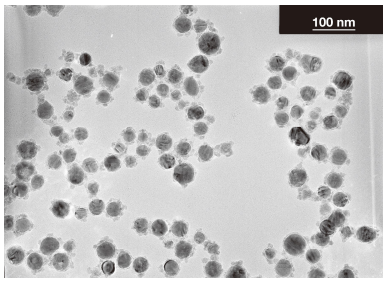
DC-50

■**低粘度インクで、 導電・抗菌などの用途に適応**
Low-viscosity ink. Suitable for conductive and antibacterial applications.

DC-50R

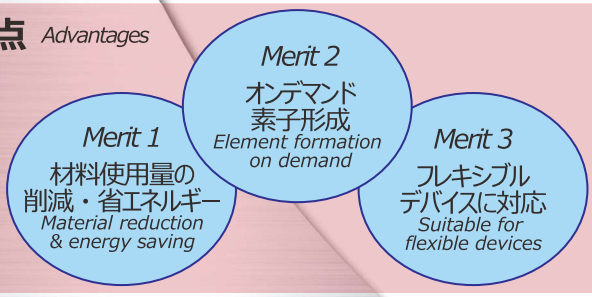
■***DC-50* に独自成分を配合し、 導体膜の高い平滑性と厚膜化を実現**
High smoothness and thickening of the conductor film are achieved by blending DC -50 with a component developed by us.

■本品は京都大学とともに、 文部科学省地域イノベーションクラスタープログラム（グローバル型）京都環境ナノクラスター事業で開発したものです。
This product is supported by MEXT and ASTEM and was developed in cooperation with Kyoto University.

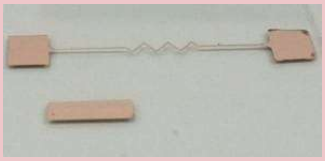


***DC-50 TEM* 像**
TEM image of copper oxide nanoparticle

利点 *Advantages*



適用例 *Applications*


DC-50 導体化処理後の外観
After conductor treatment（DC-50）

■電子機器の高性能・小型化に伴う微細な電子部品素子の配線用に
For wiring of fine electronic component elements.

■導電・放熱・抗菌など機能性コンポジット用フィラーに
For fillers of conductivity, heat dissipation, and antibacterial properties.

■導電ペースト用のフィラーに
For conductive paste.

FUKUDA
FUKUDA METAL FOIL & POWDER CO.,LTD.
福田金属箔粉工業株式会社

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